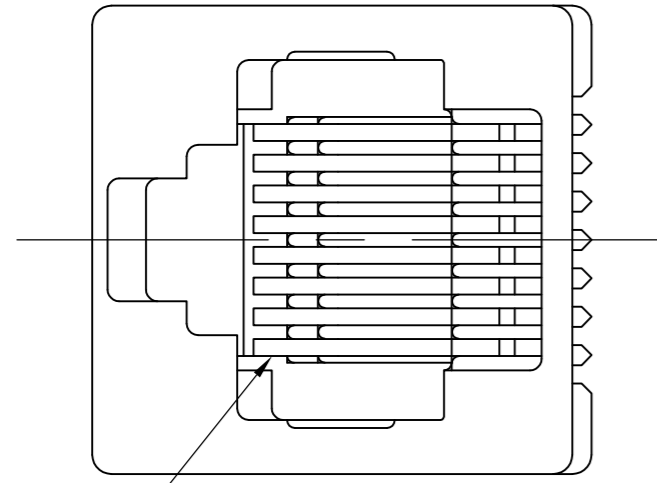


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LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION		DATE	DWN	APVD	
AA	00	B	ECO-07-017784	14AUG07	LAM	PR	

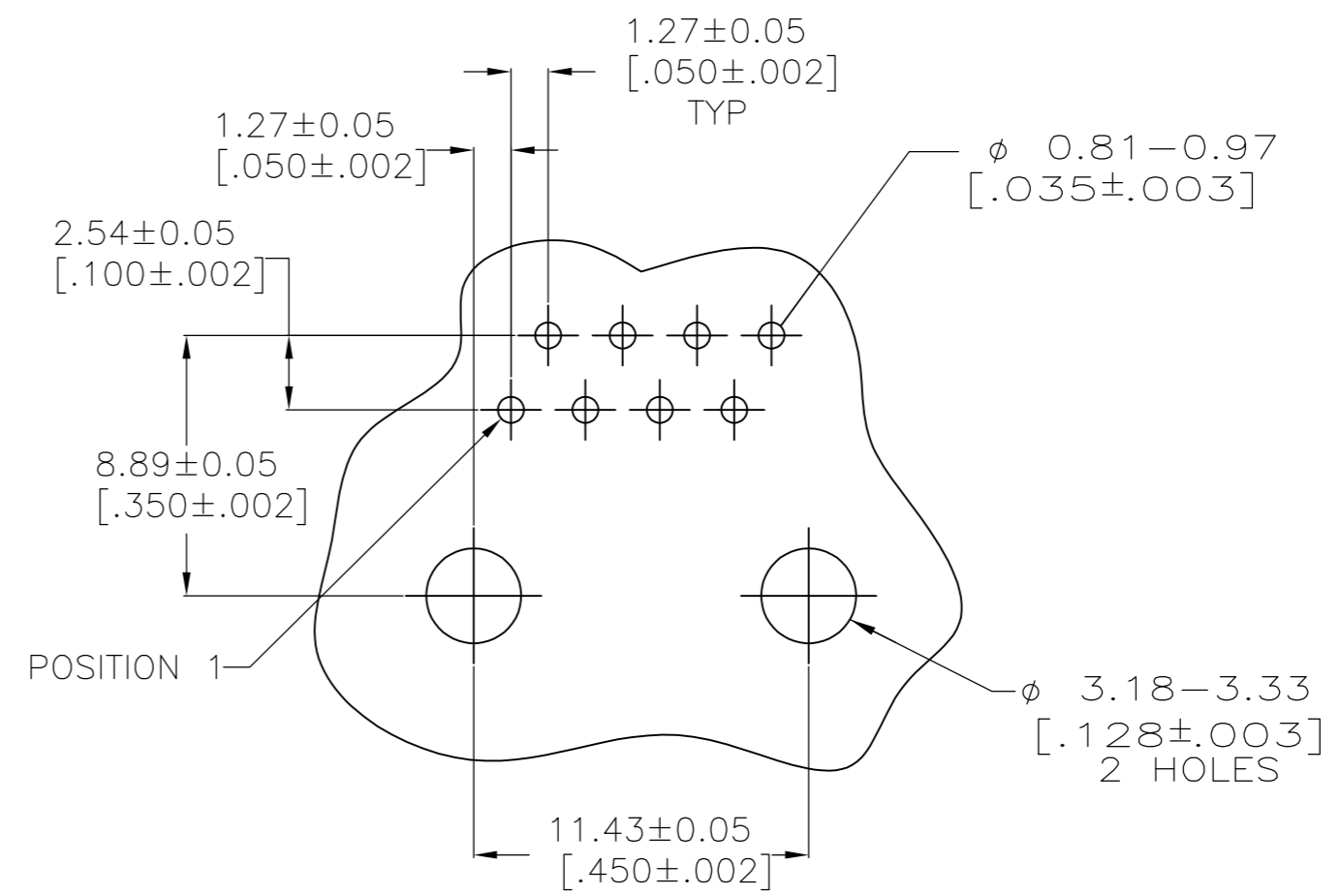
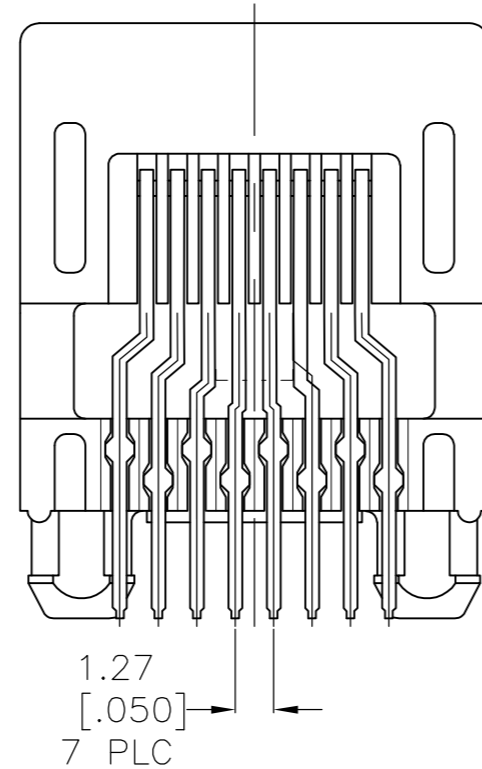
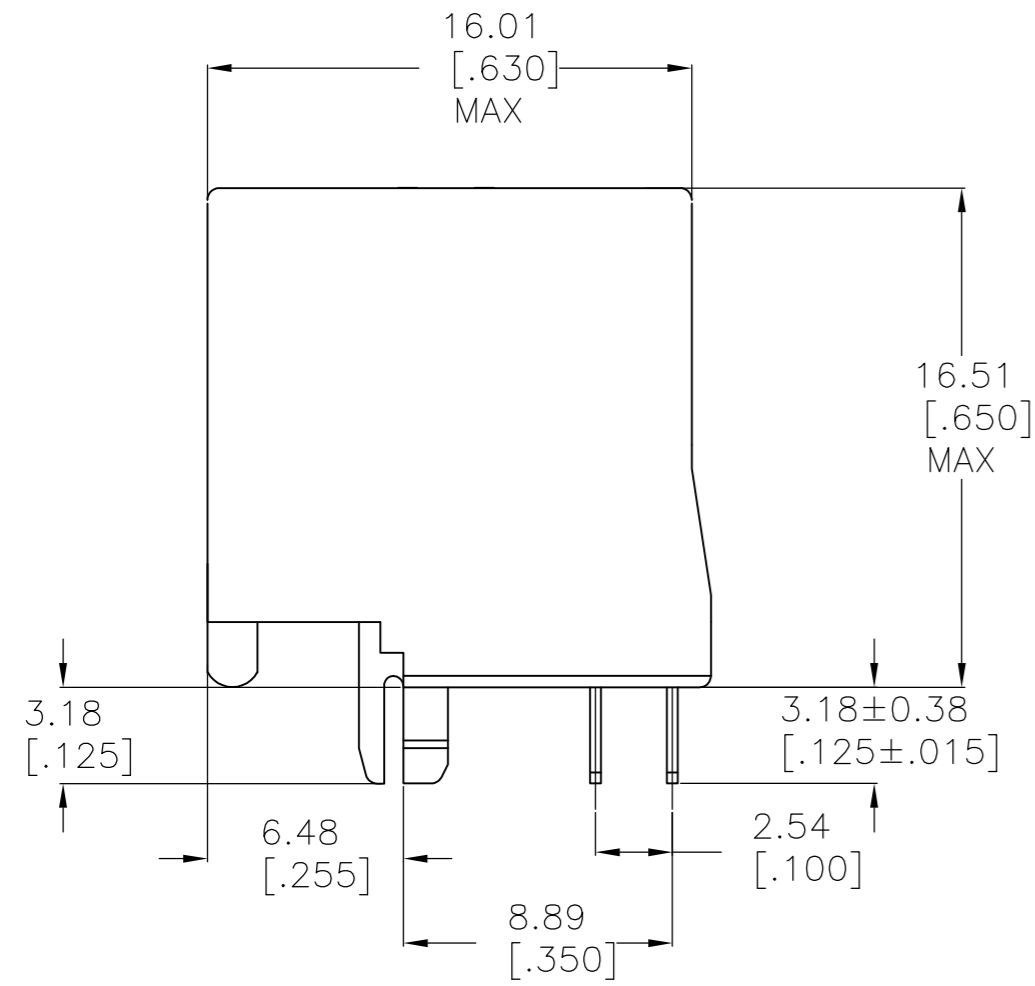


2

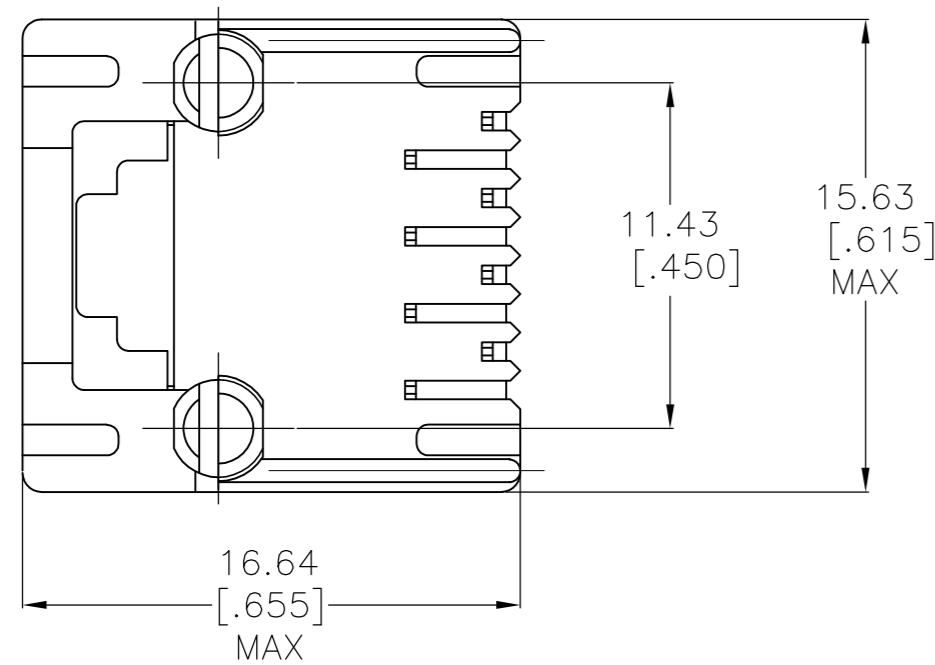
- MATERIAL: HOUSING - HTN MOLDING COMPOUND, UL 94V-0 COLOR: BLACK
 TERMINAL - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27 μ m [.000050] MIN THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA, 3.81 μ m [.000150] MIN THICK MATTE TIN IN SOLDER AREA AND 1.27 μ m [.000050] MIN THICK NICKEL UNDERPLATE

2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81 PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

- BULK PACKAGED IN A TRAY.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 COMPONENT SIDE



THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN L.A.MAYER 06JUN2005	Tyco Electronics Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		CHK P.RECCE 14AUG2007	NAME S. FLICKINGER	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER 14AUG2007	PRODUCT SPEC 108-1163	
0 PLC ± -		APPLICATION SPEC 114-2048		SIZE A2
1 PLC ± -		WEIGHT -		CAGE CODE 00779
2 PLC ± 0.13[.005]		CUSTOMER DRAWING		DRAWING NO C=5569284
3 PLC ± -		SCALE 4:1		SHEET 1 OF 1
4 PLC ± -		REV B		RESTRICTED TO -
ANGLES ± -				
FINISH SEE NOTE 1				

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)